

Docket No.

OCT 05 2001
09531163-0X



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION

Hiroyuki YANO, et al.

SERIAL NO: 09/531,163

GAU: 1756

FILED: March 17, 2000

EXAMINER: D. DEO

FOR: AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL MECHANICAL POLISHING USED FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF EMBEDDED WIRING

INFORMATION DISCLOSURE/RELATED CASE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

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OCT 11 2001

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SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- Each item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

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Respectfully submitted,

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Re: In re Application of: Hiroyuki YANO, et al.
U.S. Application Serial No.: 09/531,163
Filing Date: March 17, 2000
For: AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF
EMBEDDED WIRING
Group Art Unit: 1765
Examiner: D. DEO

STATEMENT OF RELEVANCY

The references cited on the attached Form PTO-1449:

The two catalogues describe the IC1000 pad.